LNP™ THERMOCOMP™ COMPOUND JF004Z

JF-1004 EHV

DESCRIPTION

LNP THERMOCOMP JF004Z is a compound based on Polyethersulfone resin containing Glass Fiber. Added features of this material include: HV.

TYPICAL PROPERTY VALUES

Revision 20191213

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, break, 5 mm/min	120	MPa	ISO 527
Tensile Strain, break, 5 mm/min	2.7	%	ISO 527
Tensile Modulus, 1 mm/min	6700	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	178	MPa	ISO 178
Flexural Modulus, 2 mm/min	5800	MPa	ISO 178
IMPACT			
Izod Impact, unnotched 80*10*4 +23°C	40	kJ/m²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	7	kJ/m²	ISO 180/1A
THERMAL			
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	225	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	221	°C	ISO 75/Af
PHYSICAL			
Mold Shrinkage on Tensile Bar, flow	0.25 – 0.45	%	SABIC method
Density	1.51	g/cm³	ISO 1183
INJECTION MOLDING			
Drying Temperature	120 – 150	°C	
Drying Time	4	hrs	
Maximum Moisture Content	0.05	%	
Melt Temperature	355 – 370	°C	
Front - Zone 3 Temperature	370 – 380	°C	
Middle - Zone 2 Temperature	360 – 370	°C	
Rear - Zone 1 Temperature	345 – 355	°C	
Mold Temperature	140 – 150	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	60 – 100	rpm	

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